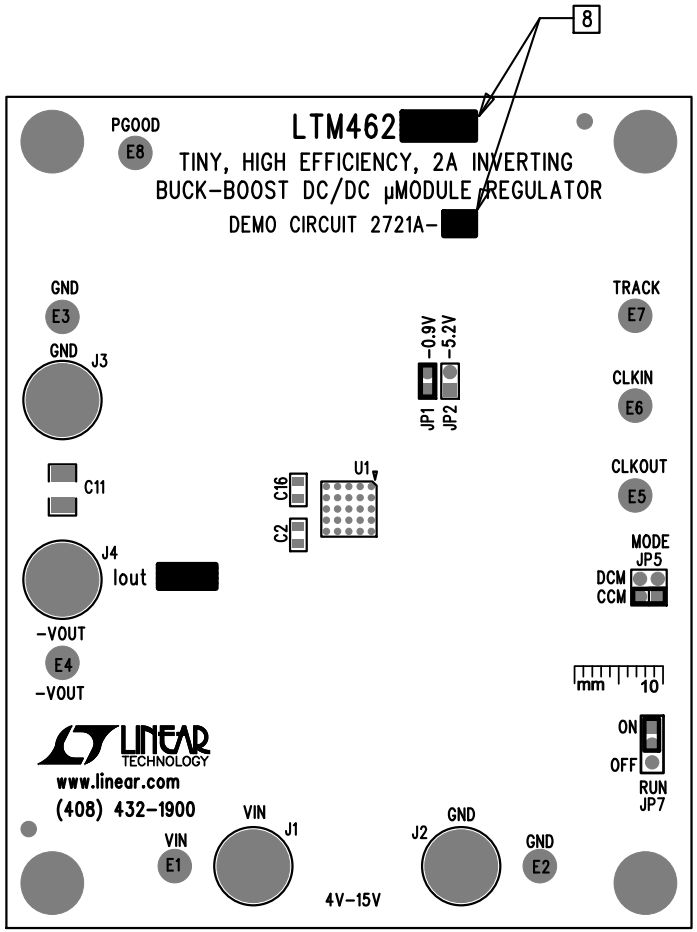
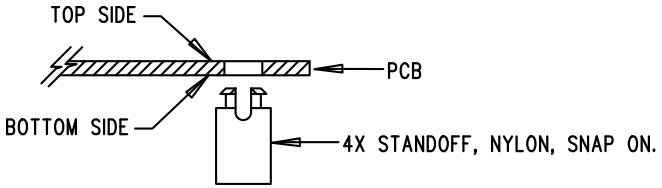
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
–	2	PRODUCTION	SAM Y.	8-25-17



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



8 MARK EACH LTC PART NUMBER AND ASSEMBLY TYPE WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY	U1	Iout
-A	LTM4623EV	2A
-B	LTM4625EY	3A

APPROVALS	
PCB DES.	LT
APP ENG.	SAM Y.
SCALE = NONE	

LINEAR TECHNOLOGY
1630 MCCARTHY BLVD
MILPITAS, CA 95035
PH: (408)432-1900
www.linear.com

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FOR CUSTOMER USE ONLY

TITLE: TOP ASSEMBLY DRAWING
TINY, HIGH EFFICIENCY, 2A INVERTING
BUCK-BOOST DC/DC µMODULE REGULATOR

SIZE	IC NO.	REV.
N/A	LTM4623EV/LTM4625EY DEMO CIRCUIT 2721A	2

FILENAME: DC2721A-2.PCB SHT 1 OF 2